



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-04-28
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STD46N6F7	CQDP*OD62T52	A	SHENZHEN B/E	2016-04-28
Amount		UoM	Unit type	ST ECOPACK Grade
330.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	6.5-6.1-2.3	3	GULL WING	
Comment	TO 252 DPAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	CQP*OD62T52					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.454	mg	supplier	die	Silicon (Si)	7440-21-3		0.409	mg	900662	1236
				supplier	metallization	Aluminium (Al)	7429-90-5		0.018	mg	39734	55
				supplier	Passivation	Silicon Oxide	7631-86-9		0.008	mg	17660	24
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	2208	3
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.014	mg	30905	42
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.001	mg	2208	3
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.003	mg	6623	9
				supplier	alloy	Copper (Cu)	7440-50-8		164.152	mg	995198	497430
Leadframe	Copper & its alloys	164.944	mg	supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.330	mg	2001	1000
				supplier	alloy	Cobalt (Co)	7440-48-4		0.462	mg	2801	1400
				JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.706	mg	954673	5170
Soft solder	Solder	1.787	mg	supplier	solder	Silver (Ag)	7440-22-4		0.045	mg	25182	136
				supplier	solder	Tin (Sn)	7440-31-5		0.036	mg	20145	109
Bonding wires	Other inorganic materials	0.342	mg	supplier	wire	Copper (Cu)	7440-50-8		0.342	mg	1000000	1036
				supplier	wire	Copper (Cu)	7440-50-8		0.342	mg	1000000	1036
Encapsulation	Other Organic Materials	161.428	mg	supplier	mold compound	Silica, vitreous	60676-86-0		141.250	mg	875003	428030
				supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-b	EC 413-900-7		6.457	mg	39999	19567
				supplier	mold compound	Epoxy Resin	25068-38-6		4.843	mg	30001	14676
				supplier	mold compound	phenol resin	29690-82-2		8.071	mg	49998	24458
				supplier	mold compound	Carbon black	1333-86-4		0.807	mg	4999	2445
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3167